

SML100HB06

Attributes:

- aerospace build standard
- high reliability
- lightweight
- metal matrix base plate
- AlN isolation


**Maximum rated values/
Electrical Properties**

Collector-emitter Voltage		V_{ces}	600	V
DC Collector Current	$T_c=75C$ $T_c=25C$	$I_{c, nom}$ I_c	100 130	A
Repetitive peak Collector Current	$tp=1msec, T_c=75C$	I_{crm}	200	A
Total PowerDissipation	$T_c=25C$	P_{tot}	340	W
Gate-emitter peak voltage		V_{ges}	+/-20	V
DC Forward Diode Current		I_f	100	A
Repetitive Peak Forward Current	$tp=1msec$	I_{frm}	200	A
I^2t value per diode	$V_f=0V, tp=10msec,$ $T_vj=125C$	I^2_t	1250	A^2sec
Isolation test voltage	RMS, 50Hz, $t=1min$	V_{isol}	2500	V

Collector-emitter saturation voltage	$I_c=75A, V_{ge}=15V, T_c=25C$ $I_c=75A, V_{ge}=15V, T_c=125C$	$V_{ce(sat)}$		1.95 2.2	2.45	V
Gate Threshold voltage	$V_{ce}=V_{ge}, T_vj=25C$	$V_{ge(th)}$	4.5	5.5	6.5	V
Input capacitance	$f=1MHz, T_vj=25C, V_{ce}=25V,$ $V_{ge}=0V$	C_{ies}		4.3		nF
Reverse transfer Capacitance	$f=1MHz, T_vj=25C, V_{ce}=25V,$ $V_{ge}=0V$	C_{res}		0.4		nF
Collector emitter cut off current	$V_{ce}=600V, V_{ge}=0V, T_vj=25C$ $V_{ce}=600V, V_{ge}=0V, T_vj=125C$	I_{ces}		1 1	500	μA
Gate emitter cut off current	$V_{ce}=0V, V_{ge}=20V, T_vj=25C$	I_{ges}			400	μA



Turn on delay time	Ic=100A, Vcc=300V Vge=+/15V,Rg=2.2Ω,Tvj=25C Vge=+/-15V,Rg=2.2Ω,Tvj=125C	$t_{d,on}$		25 26		nsec nsec
Rise time	Ic=100A, Vcc=300V Vge=+/-15V,Rg=2.2Ω,Tvj=25C Vge=+/-15V,Rg=2.2Ω,Tvj=125C	t_r		10 11		nsec nsec
Turn off delay time	Ic=100A, Vcc=300V Vge=+/-15V,Rg=2.2Ω,Tvj=25C Vge=+/-15V,Rg=2.2Ω,Tvj=125C	$t_{d,off}$		130 150		nsec nsec
Fall time	Ic=100A, Vcc=300V Vge=+/-15V,Rg=2.2Ω,Tvj=25C Vge=+/-15V,Rg=2.2Ω,Tvj=125C	t_f		20 30		nsec nsec
Turn energy loss per pulse	Ic=75A,Vce=300V,Vge=15V Rge=2.7Ω,Tvj=125C,L=35nH	E_{on}		1.0		mJ
Turn off energy loss per pulse	Ic=75A,Vce=300V, Vge=15V Rge=Ω,Tvj=125C,L=30nH	E_{off}		2.9		mJ
SC Data	$t_p \leq 10\mu\text{sec}$, $V_{ge} \leq 15V$ $T_{vj} \leq 125C$, $V_{cc} = 360V$, $V_{ce(max)} - V_{ces} - L \frac{di}{dT}$	I_{sc}		450		A
Stray Module inductance		$L_{\sigma ce}$		40		nH
Terminal-chip resistance		R_c		1.0		mΩ

Diode characteristics

Forward voltage	Ic=75A,Vge=0V, Tc=25C Ic=75A,Vge=0V, Tc=125C	V_f		1.25 1.2	1.6	V
Peak reverse recovery current	If=75A, -di/dt=3000A/μsec Vce=300V,Vge=-10V,Tvj=25C Vce=300V,Vge=-10V,Tvj=125C	I_{rm}		150 180		A
Recovered charge	If=75A, -di/dt=3000A/μsec Vce=600V,Vge=-10V,Tvj=25C Vce=600V,Vge=-10V,Tvj=125C	Q_r		7.7 13		μC
Reverse recovery energy	If=75A, -di/dt=3000A/μsec Vce=600V,Vge=-10V,Tvj=25C Vce=600V,Vge=-10V,Tvj=125C	E_{rec}		3.2		mJ mJ



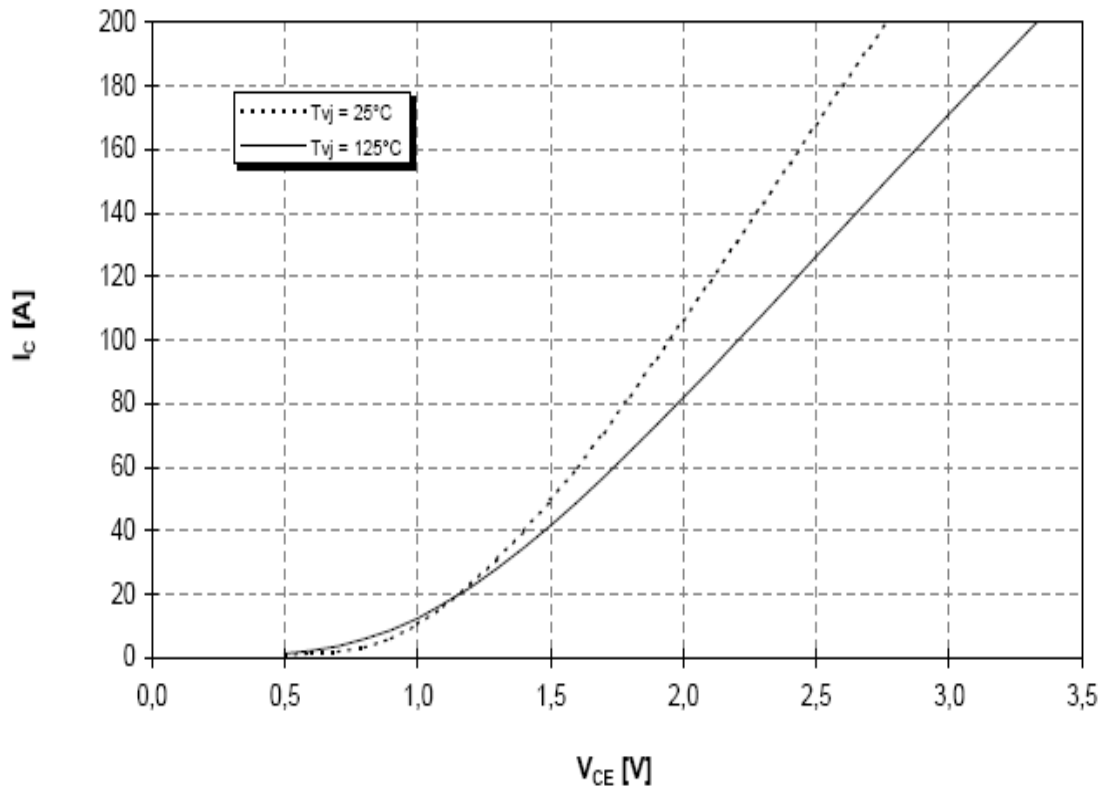
Thermal Properties

Min Typ Max

Thermal resistance junction to case	Igibt Diode	$R_{\theta J-C}$			0.37 0.67	K/W
Thermal resistance case to heatsink		$R_{\theta C-HS}$		0.03		K/W
Maximum junction temperature		T_{vj}			150	C
Maximum operating temperature		Top	-40		125	C
Storage Temperature		T_{stg}	-40		125	C

Output characteristic (typical)

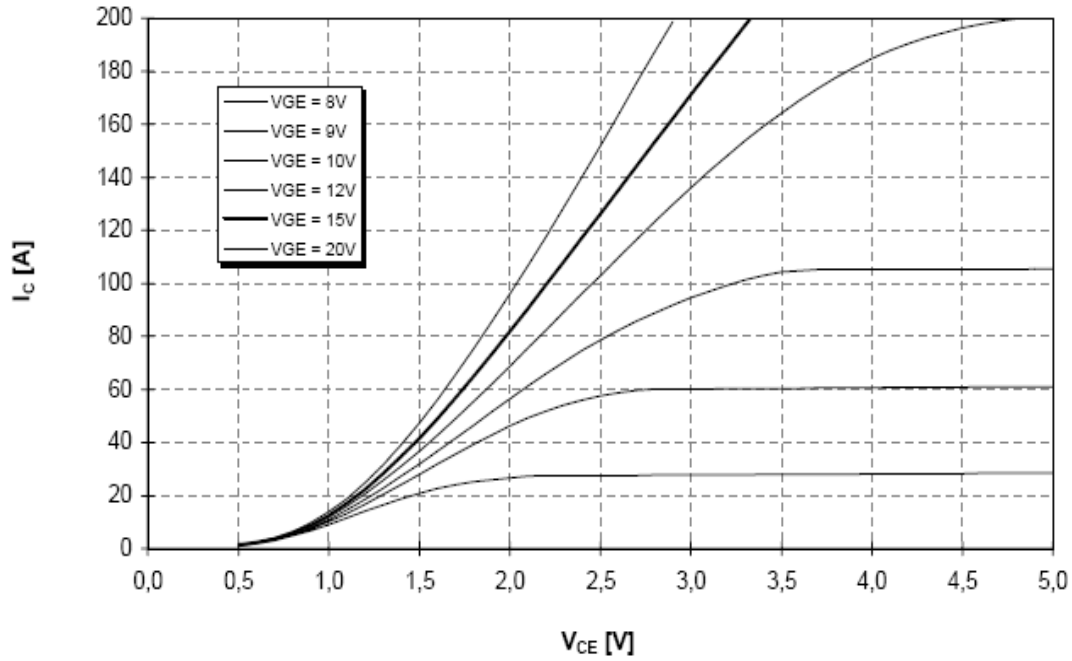
$V_{GE} = 15V$





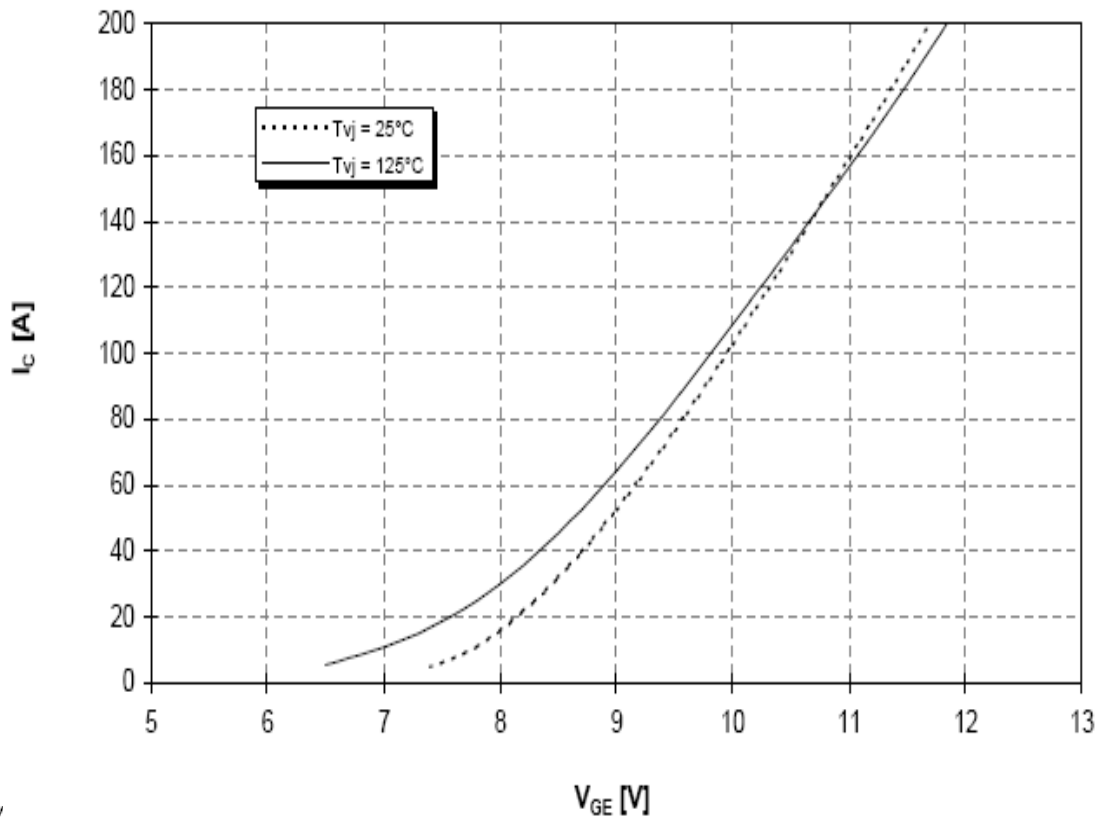
Output characteristic (typical)

$T_{vj} = 125^{\circ}\text{C}$



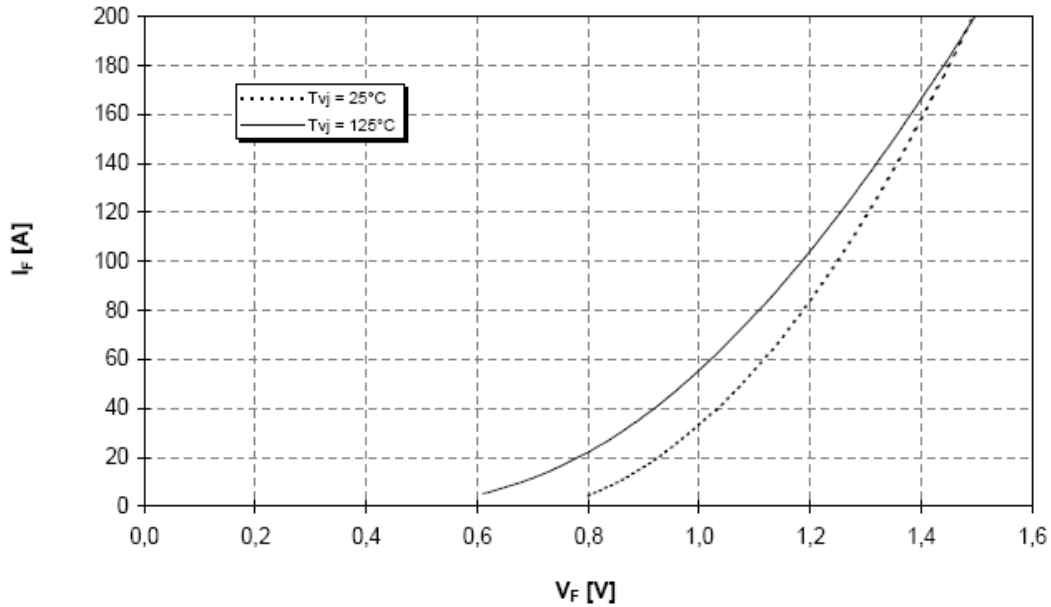
Transfer characteristic (typical)

$V_{ce} = 20V$



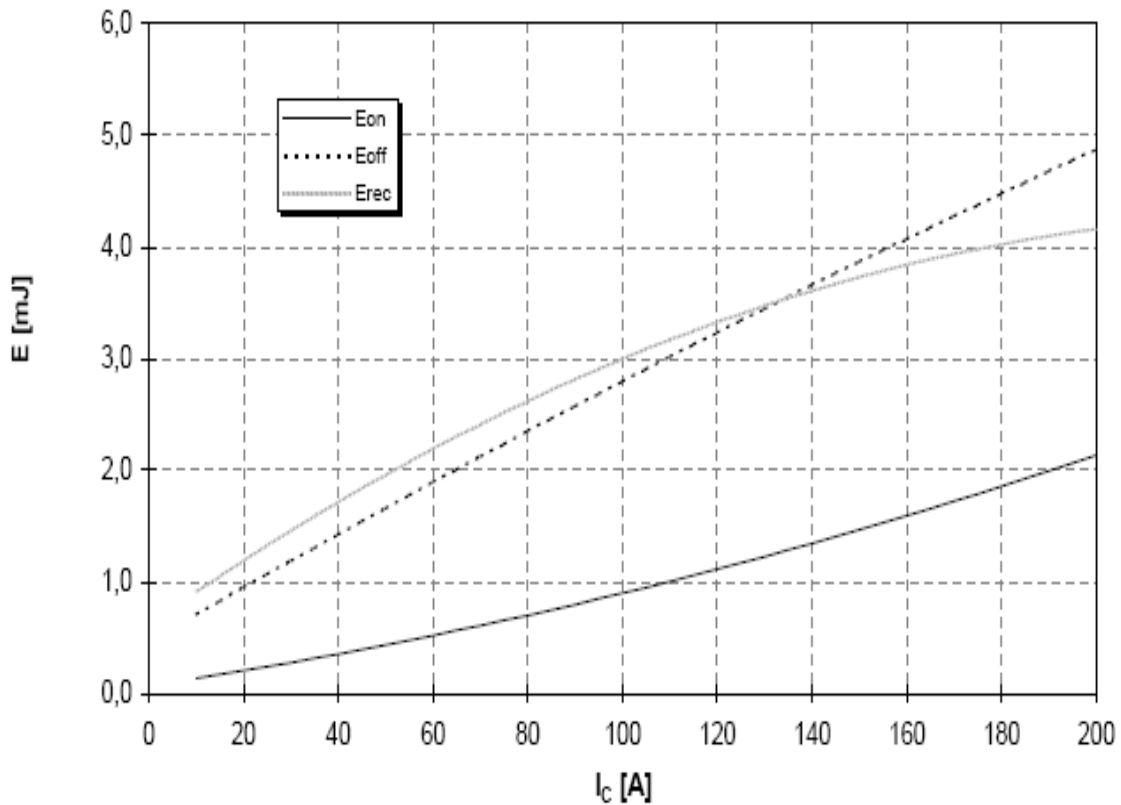


Forward characteristic of inverse diode (typical)



Switching losses (typical)

$R_{\theta,on} = 2,2\Omega$, $R_{\theta,off} = 2,2\Omega$, $V_{CC} = 300\text{V}$, $T_{vj} = 125^\circ\text{C}$

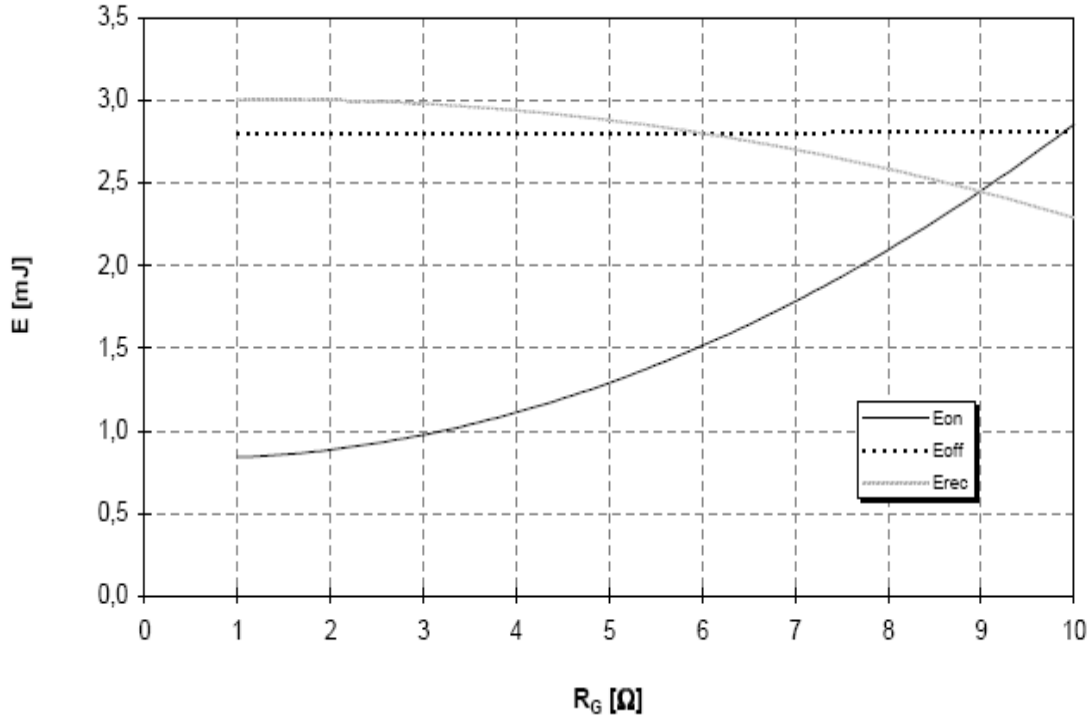


Semelab Plc reserves the right to change test conditions, parameter limits and package dimensions without notice. Information furnished by Semelab is believed to be both accurate and reliable at the time of going to press. However Semelab assumes no responsibility for any errors or omissions discovered in its use. Semelab encourages customers to verify that datasheets are current before placing orders



Switching losses (typical)

$I_C = 100A$, $V_{CE} = 300V$, $T_V = 125^\circ C$



Reverse bias safe operation area (RBSOA)

$V_{GE} = +15V$, $R_{G,off} = 2,2\Omega$, $T_V = 125^\circ C$

